

***“Characterization of the Thermal and Mechanical Response
of GaN High Electron Mobility Devices”***

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*Thursday, January 13, 2011
3:00 pm, Birck 1001*

Abstract: The high power density in AlGaIn/GaN high electron mobility devices (HEMTs) leads to intense heating which is detrimental to their performance and reliability. The heating is primarily caused by the generation of longitudinal optical phonons which build-up in the channel resulting in the hot phonon effect. Although high thermal conductivity substrates have been used to dissipate heat from these devices (e.g., SiC, diamond), the self-heating in AlGaIn/GaN heterostructures remains a critical issue in the success of their commercialization. The large phononic band gap provides additional resistance in dissipating the thermal energy from these devices which has received little attention from researchers. In addition, the stress fields induced in AlGaIn/GaN HEMTs that includes residual stresses, thermoelastic stresses, and inverse piezoelectric stresses, also significantly impacts the device reliability. However, there remains few measurements and understanding of the stress and temperature fields in devices and how they relate to device reliability.

In this talk, an investigation of the temperature rise and stress evolution in AlGaIn/GaN HEMTs using micro-Raman spectroscopy and micro-photoluminescence will be presented. Micro-Raman was utilized to obtain a high spatial resolution temperature profile within the active region by probing changes in the optical phonons in the channel. A method to deconvolute thermoelastic stress and temperature fields in the devices based on measuring multiple characteristics of phonon peak positions and linewidths will be presented. A comparative analysis of the stress measured by means of micro-Raman spectroscopy and micro-photoluminescence was also performed to provide depth dependent stress values down to a 30 nm depth resolution. These data are then correlated with electrical performance of the devices. Finally, efforts to model the electro-thermo-mechanical response of the devices will be presented.

Bio: Samuel Graham is an Associate Professor of Mechanical Engineering at the Georgia Institute of Technology where he serves as the Associate Director of the NSF Science and Technology Center CMDITR. Prior to this, he was a staff member at Sandia National Laboratories. His research activities include the characterization of GaN semiconductors for RF and optoelectronic applications, packaging of organic electronics, and thermal management and reliability of electronic devices.

